IN THE CLAIMS:

Please cancel Claims 1-11 and 19 without prejudice or disclaimer of the subject matter recited therein.

Please amend Claims 13, 18, 20, 21 and 24 as follows.

1-12. (Canceled).

13. (Currently Amended) A method of manufacturing an airtight container according to Claim 21, wherein the step of forming the closed bonding line comprises performing the airtight bonding of each of the substrate [[an]] and the member with the seal bonding material for ~~each~~ a small region at a time.

14. (Previously Presented) A method of manufacturing an airtight container according to Claim 21, wherein the substrate is one substrate of a pair of mutually opposing substrates, and the member is a frame fixed to the other substrate.

15. (Previously Presented) A method of manufacturing an airtight container according to Claim 21, wherein the step of forming the closed bonding line is performed under a vacuum atmosphere.

16. (Previously Presented) A method of manufacturing an airtight container according to Claim 21, wherein the corner portion comprises a groove portion formed therein in the state where the setting step is performed.

17. (Previously Presented) A method of manufacturing an airtight container according to Claim 21, further comprising forming a base film in a location where the seal bonding material is to be arranged, and the base film being formed of a material having a good wettability with the seal bonding material.

18. (Currently Amended) A method of manufacturing an airtight container according to Claim 21, wherein when ~~the~~ a seal bonding member, which is obtained as the seal bonding material solidifies at a predetermined position of the bonding line, is seen in cross section taken along a direction perpendicular to a longitudinal direction of the bonding line, in the corner portion defined by the substrate and the above-mentioned member, a penetration length of the seal bonding member penetrating between mutually opposed surfaces of the substrate and the above-mentioned member is shorter than a contact length over which the seal bonding member contacts the member set to abut on the substrate.

19. (Canceled)

20. (Currently Amended) A method of manufacturing an image display apparatus[[,]] ~~comprising the steps of:~~ forming having an airtight container for containing display devices, ~~by using the method of manufacturing an airtight container at set forth in Claim 21~~ comprising the steps of:

setting a member for defining an airtight space together with a substrate to abut on the substrate;

supplying a seal bonding material of indium or indium alloy to a corner portion formed by the substrate and the member, or to a portion to be the corner portion formed in the setting step;

after the step of setting, under a condition of heating the member at a temperature equal to or lower than 130°C and equal to or lower than a temperature at which the seal bonding material can performing bonding, heating locally the seal bonding material to a temperature equal to or higher than a temperature at which the seal bonding material can perform bonding, wherein the seal bonding material heated is then cured, so as to perform airtight bonding of each of the substrate and the member with the seal bonding material to form a closed bonding line; and

forming the display devices.

21. (Currently Amended) A method of manufacturing an airtight container, comprising the steps of:

setting a member for defining an airtight space together with a substrate to abut on the substrate;

supplying a seal bonding material of indium or indium alloy to a corner portion formed by the substrate and the member ~~of~~, or to a portion to be the corner portion formed in the setting step; and

~~at a state of setting the member to abut on the substrate~~ after the step of setting, under a condition of heating the member at a temperature equal to or lower than 130°C and equal to or lower than a temperature at which the seal bonding material can perform bonding, heating locally the seal bonding material to a temperature equal to or higher than a temperature at which the seal bonding ~~member~~ material can perform ~~bonded~~ bonding,

wherein, the heated seal bonding material ~~heated~~ is then cured, so as to perform airtight bonding of each of the substrate and the member with the seal bonding material to form a closed bonding line.

22. (Previously Presented) A method of manufacturing an airtight container according to claim 21, wherein in the step of heating locally, the temperature at which the member is heated to is equal to or lower than 110°C.

23. (Previously Presented) A method of manufacturing an airtight container according to claim 21 or 22, wherein in the step of heating locally, the temperature at which the member is heated to is equal to or higher than 90°C.

24. (Currently Amended) A method of manufacturing an airtight container according to claim 21, wherein in the step of heating locally, the ~~heating~~ member is ~~performed~~ heated by heating the entire airtight container.